Special Issue

Selected Papers from the 4th International Electronic Conference on *Applied Sciences*

Message from the Guest Editor

This Special Issue is in cooperation with the 4th International Electronic Conference on Applied Sciences, organized by Applied Sciences, from 27 October–10 November 2023 on the MDPI Sciforum platform. We welcome extended versions of the presented papers at this conference to be published in this Special Issue. Conference Link: https://sciforum.net/event/ASEC2023.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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